

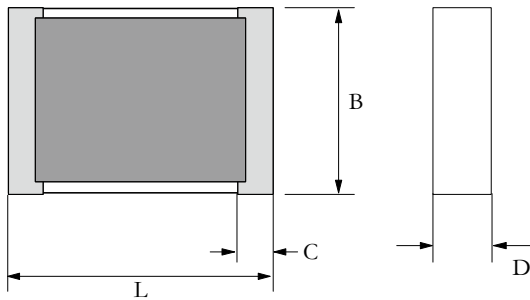
● Features

- I Thick film technology
- II Close tolerance
- III Low TCR

● Applications

- I Computers
- II Telecom and wireless
- III Precision meters and instruments
- IV Electrical devices

● Dimensions



Type	Dimensions(mm)			
	L	B	D	C
CRP0805	2.0 \pm 0.10	1.25 \pm 0.10	0.50 \pm 0.10	0.35 \pm 0.10
CRP1206	3.10 \pm 0.10	1.60 \pm 0.10	0.55 \pm 0.10	0.45 \pm 0.10

L=length, B=width, D=Thickness
C=width of wraparound(in mm)

● Ordering Information

Example:

CRP	0805	125	B	100K Ω	C3
(1)	(2)	(3)	(4)	(5)	(6)
Series Name	Style	Power Rating	Resistance Tolerance	Resistance	T.C.R

(1)Type: CRP SERIES

(2)Style:0805,1206

(3)Power Rating: 125=125mW,250=250mW

(4)Tolerance: B= \pm 0.1%,C= \pm 0.25%,D= \pm 0.5%,F= \pm 1%

(5)Resistance Value:100K Ω =100K Ω

(6)T.C.R:C4= \pm 20ppm/ $^{\circ}$ C ,C3= \pm 25ppm/ $^{\circ}$ C ,C2= \pm 50ppm/ $^{\circ}$ C

If no requirements for TCR and taping,the standard TCR(highest value in table)will be supplied and packaging is bulk.

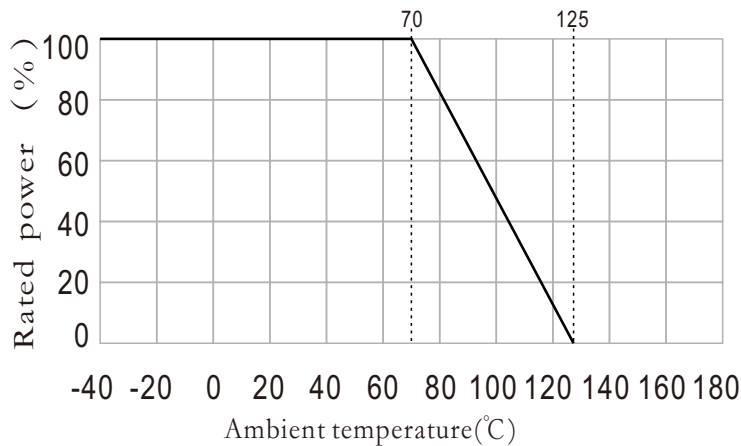
● Reference Standards

JISC 5201-1

● Applications And Ratings

Type	Power(W)	T.C.R(ppm/ $^{\circ}$ C)	Resistance Range	Limiting Voltage (DC or AC effective value)	Resistance Tolerance(%)	Climatic Category
CRP0805	0.125	\pm 50	1R0~10M	100V	\pm 1%	55/125/56
CRP1206	0.25	\pm 25 \pm 15		200V	\pm 0.5% \pm 0.25% \pm 0.1%	

Derating Curve



Performance

Test Items	Specifications	Test Methods(JIS C 5201-1)
Rapid change of temperature	$\Delta R \leq \pm (0.25\%R + 0.05\Omega)$	-55°C 30min/125°C 30min,5cycles
Temperature cycling	$\Delta R \leq \pm (1\%R + 0.05\Omega)$	125°C,16h/55°C,RH93±3%,24h/-55°C,2h/15~35°C,8.5kpa,1h
Endurance at 70	$\Delta R \leq \pm (1\%R + 0.05\Omega)$	70±2°C,P _R ,1000h
Leaching	$\Delta R \leq \pm (0.25\%R + 0.05\Omega)$	350±10°C,3.5±0.5s
Short time over load	$\Delta R \leq \pm (0.25\%R + 0.05\Omega)$	2.5V _R .5s
Damp heat, steady state	$\Delta R \leq \pm (1\%R + 0.05\Omega)$	40°C,RH93±3%,56d
Endurance at upper category temperature	$\Delta R \leq \pm (1\%R + 0.05\Omega)$	125°C,1000h
Solderability	≥95%	235±5°C.2±0.5s

Recommended Mounting Methods

Generally in the case of flow soldering, the soldering pad width should be 0.7 to 0.8times the width of chip resistor, in the case of reflowing soldering, the soldering pad width should be 1.0 to 1.3 times the width of chip resistor.